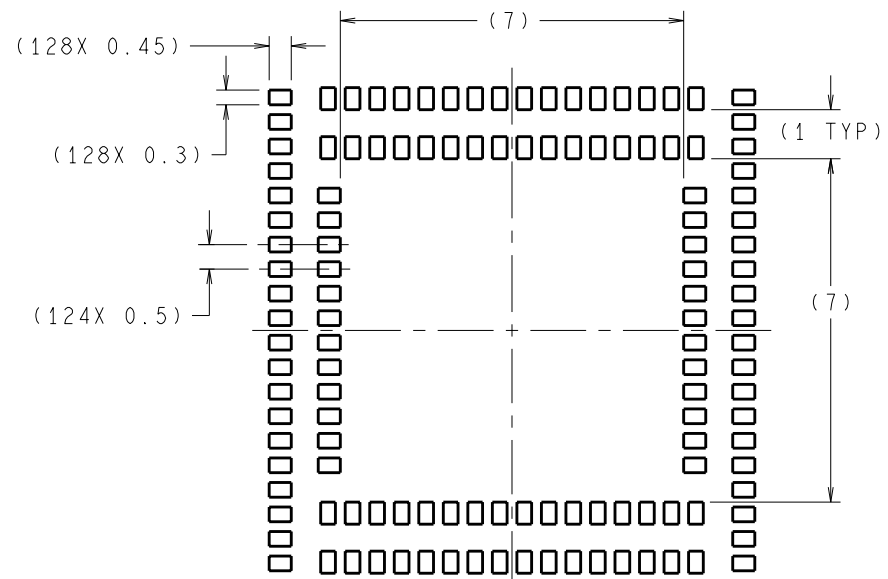
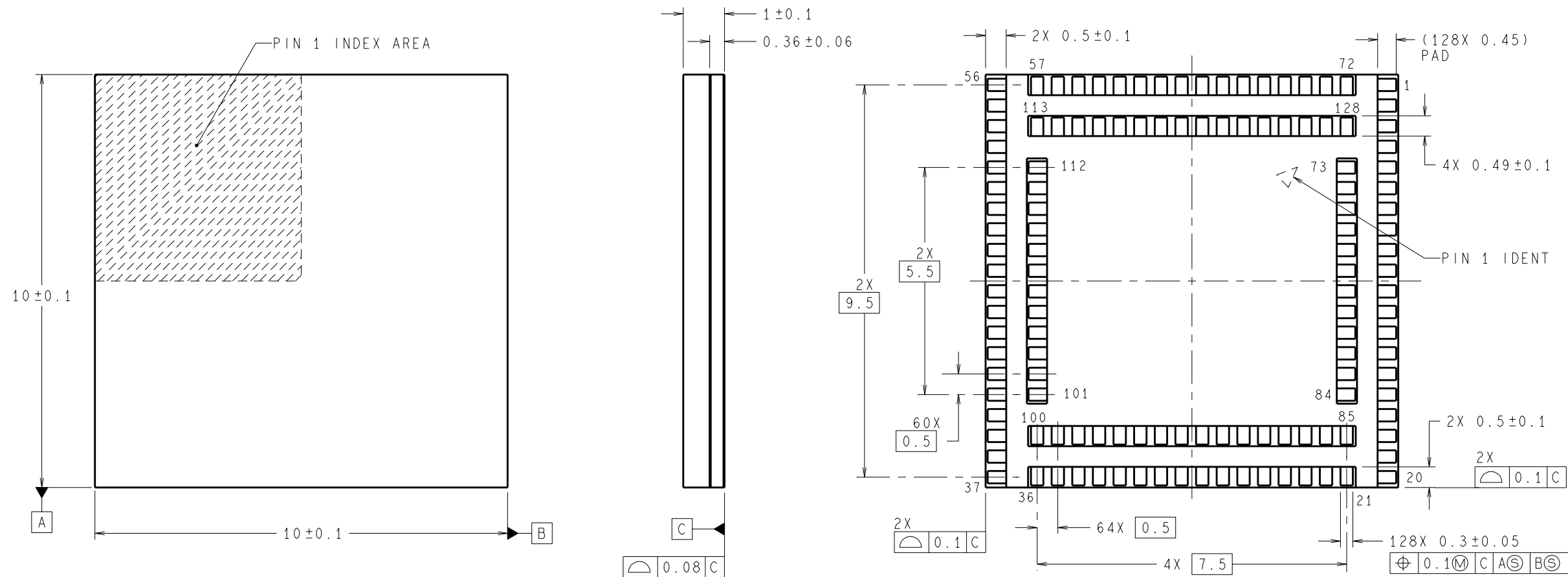


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12336	01/27/2000	TL/GN
B	ADD MISSING PADS TO LAND PATTERN	324	08/01/2001	TL/AT



DIMENSIONS ARE IN MILLIMETERS

RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS



NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
- PLATING: Cu 15 TO 20 MICROMETERS
Ni 10 ± 5 MICROMETERS
Au 1 ± 0.5 MICROMETER
- REFERENCE JEDEC MO-208, VARIATION PPEB, DATED DECEMBER 1999.

APPROVALS	DATE	National Semiconductor			
DRAWN T. LEQUANG	01/27/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DFTG. CHK. MARTA SUCHY	08/01/2001	CSP, PLASTIC, LAMINATED, 10 x 10 x 1 mm BODY, 128 L, 0.5 mm PITCH			
ENGR. CHK. ANNY TU	08/01/2001				
		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-SLB128A	REV B
		FORMERLY: N/A	SHEET 1 of 1		